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# Datasheet for ChipsemiCHSC5816

Ver1.1.5

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## Features:

- Capacitive touch panel controller, highly integrated with analog transceivers and digital Processor (SOC)
- Support mutual-capacitance, self-capacitance, hybrid sense also with noise detect
- 16 programmable TRX pin, typical with (8 TX, 8 RX) channels or (4 TX, 12 RX) channels, with displays size up to 2 inches,
- Report rate up to 250Hz
- Supports moisture detection
- Strong filtering for noise from AC charger/ common mode noise or LCD/OLED
- Low power consumption for battery application
- 32bits MCU and Software Developing Environment
- I2C interface to host
- In-system re-programmability(re-flash) support
- High ESD endurance :
  - HBM>+-7KV
  - CDM>+-1.5kV
- Supports advanced sensor/display architecture with:
  - On-cell metal mesh and ITO sensor designs
  - Curved lens designs
  - Sensor ITO pattern on lens
  - Touch controller IC on sensor Flexible Printed

## Circuit (FPC) tail

- Touch controller IC on main board
- Very narrow bezel sensor designs
  - Notched, trenched, or beveled sensors

**Package: WL CSP 2.01mmx1.99mmx0.44mm; 0.4mm ball pitch**

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## 一、 Introduction

### 1.1. General description

CHSC5816 is highly integrated single-chip mutual-capacitive touch panel controller Soc developed by CHIPSEMI, which is designed to work with mutual-capacitance type sensor and supports user-friendly gesture control and up to two-point touch with a capacitive touch panel.

Single-chip CHSC5816 supports up to 2" touch panel.

With built-in 32-bit RISC processor and CDSP module, the CHSC5816 is featured with outstanding noise immunity, fast response, low power consumption, excellent accuracy and linearity, as well as perfect waterproof performance.

CHSC5816, which operates in the  $-40^{\circ}\text{C}\sim+85^{\circ}\text{C}$  industrial temperature range, can be applied to a diverse group of portable devices, such as cellular phones, tablets, and GPS navigator.

CHSC5816 offers high-volume-assembly and high integration level. Few external components are needed to satisfy customers' ultra-low cost requirement. It's completely RoHS-compliant and 100% lead (Pb)-free.

## 1.2. Key features

Table 1- 1 Key features of CHSC5816

| Features                      | CHSC5816   |
|-------------------------------|--|
| Package                       | WLCSP 2.01mmx1.99mmx0.44mm; 0.4mm ball pitch   |
| Touch sensor                  | G/G, G/F,P/F,OGS,Ultra-thin G/F, On cell<br>(Support ITO traces; support direct bonding; support frame-less TP)  |
| Touch panel size              | 2''  |
| Response time                 | Power-on time: <75ms; Latency time for first touch: <12ms.<br>Scanning speed up to 250Hz   |
| Operating voltage             | 2.6V~3.6V  |
| Operating temperature         | -40°C~+85°C  |
| Supported channel number      | 16   |
| Power consumption             | Current-active: 2mA@200Hz FPS, 1.1mA@100Hz FPS<br>Idle : type. 25uA@30Hz FPS, max. 32uA@30Hz FPS<br>Wake up-key :Type. 24uA @100Hz, max. 28uA@100hz<br>Sleep mode:<1uA |
| ESD/latch up                  | HBM 7000V (min.), CDM 1500V (min.),latch up 200mA(min.)  |
| Multi-point touch             | Up to 2points  |
| Glove mode                    | Support  |
| Anti-interference performance | Immune to noise from RF, LCD and power supply  |

## 1.3. Sensor pin characteristics

Table 1-2 sensor pin characteristics

| Parameter          | Symbol | Condition                                  | Min | Type | Max | Unit |
|--------------------|--------|--|-----|------|-----|------|
| Mutual capacitance | Ct     | Mutual capacitance Per node                |     | 1.5  | 4   | pF   |
| Self-capacitance   | Cb     | Self-capacitance<br>Per TX or RX node      |     | 10   | 40  | pF   |
| RX impedance       | Rs     | trace +pattern resistance for<br>RX sensor |     | 20   |     | Kohm |
| TX impedance       | Rt     |  |     | 20   |     | Kohm |

**Note1:** For large self-capacitance, recommend combine with low TRX impedance.

**Note2:** For better performance, RC constant for TRX sensor is suggest below 500nS.

## 1.4. Key benefits

### (1) Anti-Interference and excellent noise-cancellation performance:

Immune to RF interferences, robust operation in noisy RF environment;

Insensitive to capacitance and environmental variety via auto calibration function;

Chipsemi's innovative adaptive-noise-cancellation technology and specially designed data processing unit can detect and silence the two noise sources which capacitive touch screen usually suffers from: display noise and charger noise.

With the powerful 32bit MCU and specific built-in hardware, both the periodic and broadband noise can be eliminated to obtain unmatched noise immunity.

### (2) Fast response time:

The power-on time for the CHSC5816 is less than 75ms;

When it is powered up, the latency time for first touch is less than 12ms;

Scanning rate up to 250Hz makes fast response available, which is especially useful for the highly demanding applications for the responding speed, such as handwriting and game.

### (3) Low power consumption:

The average current in typical case is 1.1mA@100Hz at active state,

25uA@30Hz at idle mode, and <1uA in deep sleep mode.

### (4) Excellent waterproof performance:

Water mist even droplets the surface will not influence normal operation of touch panel based on the CHSC5816. When water mist or droplets are wiped off, the touch screen can also be operated normally without extra delays. No malfunction or dummy points will be reported during water spurting and wiping process.

## 二、Pin Information

### 2.1. Pin layout

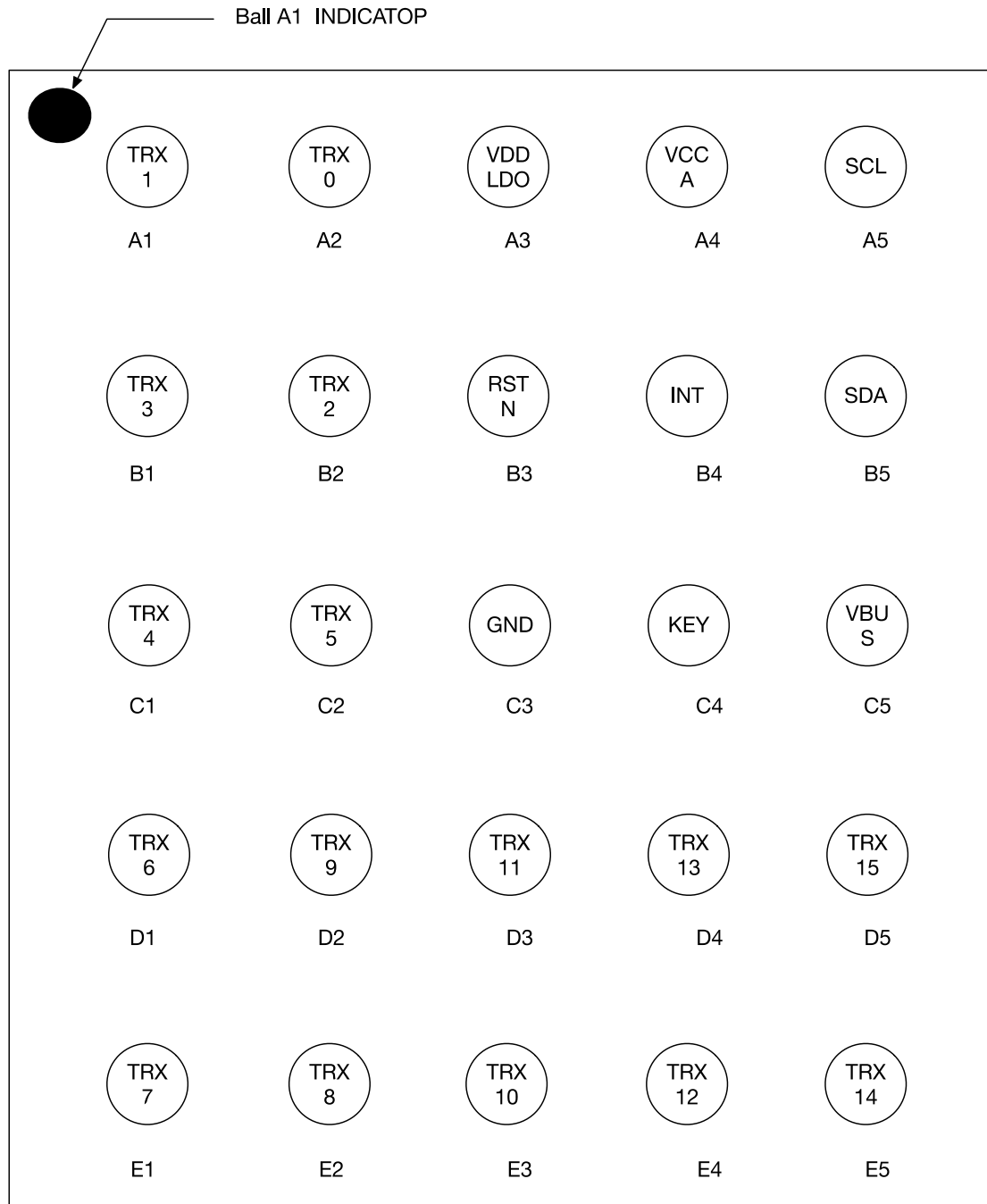


Figure 2-1 25 Ball WLCSP (TOP VIEW) assignments



## 2.2. Pin list

Table 2- 1 Pin functions for the CHSC5816

| Pin Name | X       | Y       | Pin No. | Type | Description   |
|----------|---------|---------|---------|------|---|
| TRX1     | 1795.39 | 1786.39 | A1      | I/O  | Sense input ,Drive output   |
| TRX0     | 1395.40 | 1786.39 | A2      | I/O  | Sense input ,Drive output   |
| VDDLDO   | 995.40  | 1786.39 | A3      | PWR  | Digital power 1.2V supply,<br>1uF capacitor to ground is required.                |
| VCCA     | 595.40  | 1786.39 | A4      | PWR  | Chip power supply,2.6V or 3.6V.<br>A 1uF ceramic capacitor to ground is required. |
| SCL      | 195.41  | 1786.39 | A5      | I    | I2C clock   |
| TRX3     | 1795.39 | 1386.40 | B1      | I/O  | Sense input ,Drive output   |
| TRX2     | 1395.40 | 1386.40 | B2      | I/O  | Sense input ,Drive output   |
| RSTN     | 995.40  | 1386.40 | B3      | I    | Reset Pin, zero voltage active,<br>A 0.1uF capacitor to ground is required.       |
| INT      | 595.40  | 1386.40 | B4      | I/O  | External interrupt to the host  |
| SDA      | 195.41  | 1386.40 | B5      | I/O  | I2C data  |
| TRX4     | 1795.39 | 986.40  | C1      | I/O  | Sense input ,Drive output   |
| TRX5     | 1395.40 | 986.40  | C2      | I/O  | Sense input ,Drive output   |
| GND      | 995.40  | 986.40  | C3      | G    | Ground  |
| KEY      | 595.40  | 986.40  | C4      | I    | Wake up key   |
| VBUS     | 195.41  | 986.40  | C5      | PWR  | Interface power, 1.8V or 3.6V.<br>A 1uF ceramic capacitor to ground is required.  |
| TRX6     | 1795.39 | 586.40  | D1      | I/O  | Sense input ,Drive output   |
| TRX9     | 1395.40 | 586.40  | D2      | I/O  | Sense input ,Drive output   |
| TRX11    | 995.40  | 586.40  | D3      | I/O  | Sense input ,Drive output   |
| TRX13    | 595.40  | 586.40  | D4      | I/O  | Sense input ,Drive output   |
| TRX15    | 195.41  | 586.40  | D5      | I/O  | Sense input ,Drive output   |
| TRX7     | 1795.39 | 186.41  | E1      | I/O  | Sense input ,Drive output   |
| TRX8     | 1395.40 | 186.41  | E2      | I/O  | Sense input ,Drive output   |
| TRX10    | 995.40  | 186.41  | E3      | I/O  | Sense input ,Drive output   |
| TRX12    | 595.40  | 186.41  | E4      | I/O  | Sense input ,Drive output   |
| TRX14    | 195.41  | 186.41  | E5      | I/O  | Sense input ,Drive output   |

### 2.3. Absolute maxim rating & ESD

Table 2-2 Absolute maxim rating &amp; ESD

|                            |                 |
|----------------------------|-----------------|
| VDD28 to GND               | -0.3V to +3.6V  |
| VDD18 to GND               | -0.3V to +3.6V  |
| VDD12 to GND               | -0.3V to +1.32V |
| INT/SDA/SCL to GND         | -0.3V to +3.6V  |
| TRX0~TRX11 to GND          | -0.3V to +3.6V  |
| Maxim Power dissipation    | 250mW           |
| Maxim Junction Temperature | 150℃            |
| Operating Temperature      | -40℃ to 85 ℃    |
| Storage Temperature        | -60℃ to 150 ℃   |
| HBM                        | +/-7000V (min.) |
| CDM                        | +/-1500V (min.) |

## 三、System Description

### 3.1. Block diagram

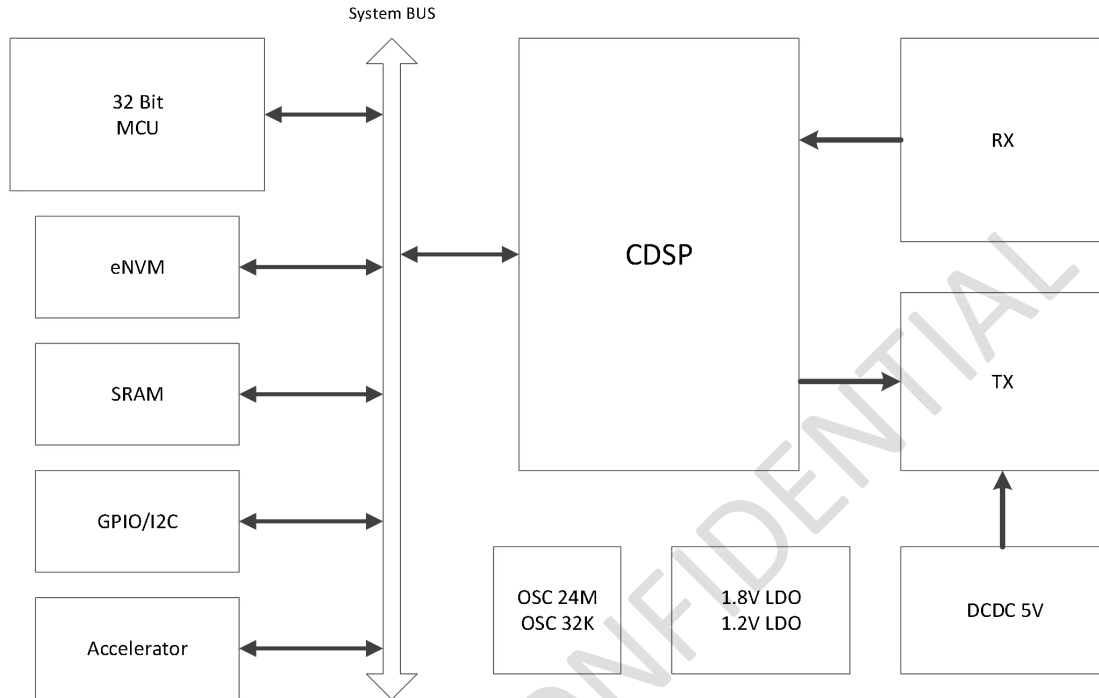


Figure 3-1 Block diagram

### 3.2. Block description

- **32bit MCU**

CHSC5816 integrates a 32bit high performance, low Power CPU.

It's Harvard structure CPU core, with a  $32 \times 32$  multiplier and a  $32/32$  divider.

- **Memory**

16KB RAM and 40KB MTP ROM.

- **GPIO/I2C interface**

INT PIN can be used as GPIO for user define, also it can generate interrupt signal.

SCL/SDA are I2C interface pins, open drain outputs.

- **Accelerator**

Hardware accelerates CTP computing.

- **CDSP**

The CHSC5816 embeds CDSP.

The CDSP configures analog front-end parameters, control analog-to-digital conversion and channel switch for flexible scanning time and sensor usage. The collected sampling data from ADC will be stored into internal SRAM and will be translated into accurate touch position information using advanced algorithms.

The CDSP integrates four control modes: mutual capacitance detection, self capacitance detection, noise detection and short detection, also it has temperature following technique.

- **TRX0~15**

CHSC5816 has 16-TRX channels that can be programmed as sensing lines or driving lines.

CHSC5816 has 12 channels for CTP sensing. The RX module is capacitive sensing channels, it includes high performance capacitive-sense amplifier and ADC that makes the capacitor quantized.

CHSC5816 has 8 channels for CTP driving. The TX module is capacitive driving channels. TX generates ordered serial signals to drive mutual capacitance panel.

CHSC5816 supports up to 64 patterns in mutual capacitive screen used 8-tx & 8-rx. It also can support 16 patterns in self capacitive screen.(Although CHSC5816 has only 12 channels for CTP sensing, but the TRX channels are programmable, so it can scan twice to finish scanning the 16 patterns).

- **Oscillator**

The CHSC5816 embeds a 24MHz RC oscillator and 32K RC oscillator.

The 24M oscillator is the clock source for MCU and CTP driving, the oscillator clock has a wide adjustment; by tuning frequency, CTP will avoid the frequency of the noise interference. The 32K oscillator is the clock source for working mode conversion timer and watch-dog monitor.

## ● Regulator

The CHSC5816 embeds two groups LDO (Low Dropout) regulators to provide lower voltage power. One is for digital core supply, and the other one is for 1.8V IO driving. Each group has two LDOs, large current driving for active mode and weak current driving for suspend and sleep mode.

## ● DCDC

The DCDC generates high voltage over supply power for TX driving, higher voltage can provide higher dynamic range for RX sensing, gets better SNR. The DCDC is recommended setting to 3V.

### 3.3. Power management

The CHSC5816 is optimized for power consumption, inside the chip it embedded PMU (power management unit) to reduce power consumption at off working state. The CHSC5816 has three working states: active/idle/deep sleep mode.

Program would control the system enter suspend or deep sleep mode, and return to active mode by interrupt signal.

Table 3-1 CHSC5816 nominal power consumption

| Operation mode | Total current(VDD28)            |
|----------------|---------------------------------|
| Active         | 1.1mA@100Hz                     |
| Idle           | Type:25uA@30Hz, max:32uA@30Hz   |
| Wake up-key    | Type:24uA@100Hz, max:28uA@100Hz |
| Sleep          | <1uA                            |

**Note:** the power consumption only show as reference. actual power consumption depend on system design requirement and the real application case.

### 3.4. Chip operation modes

For the CHSC5816, there are three operation modes available as follows: active mode, idle mode and deep sleep mode.

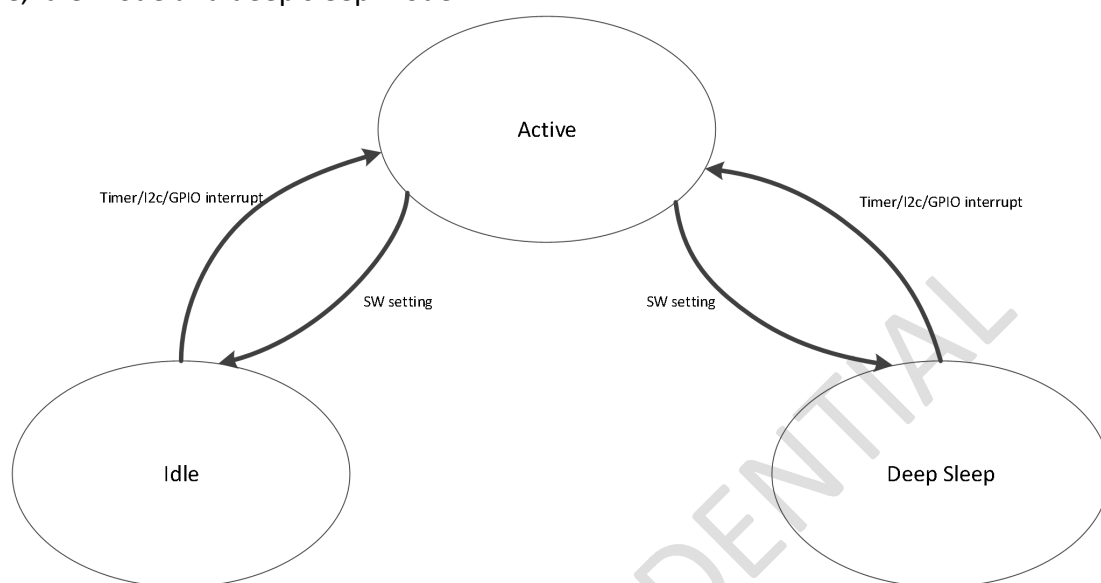


Figure 3-2 Operation mode conversion

- **Active mode**

Active mode, all module will power on, the system work at full speed with high frame report rate.

- **Idle mode**

At this mode, system detect the touch event with fast response ability, Once Touch event is detected, the system recover to active mode. The responding time can be program from 10mS~100mS by firmware.

- **Deep Sleep mode**

At deep sleep mode, the CHSC5816 will power down MCU and CTP functions and provide minimum current maintain necessary state without loss. At this mode, the CHSC5816 will consume less then 1uA current at 2.8V power supply.

I2C, INT, or inner timer can be used to wake up the system.

## 四、CTP function

The CTP is the core of capacitance detection, with high accuracy analog front end (RX, TX) and powerful computation of CDSP. The CTP provides mutual capacitance detection, self capacitance detection, noise detection and short detection mode. Also the CTP has temperature following technology to fit temperature variation.

### 4.1. Mutual capacitance mode

At mutual capacitance detection mode, the TX module outputs pulse signal, and the RX module receive it via mutual capacitance on the panel. When user touches the screen, mutual capacitance will increase, the CTP will detect capacitance changing, and mark it as contract.

Mutual capacitance detection supports large range up to 4pF, it has enough sensitive circuit to ensure the detection accuracy. It also integrate smooth filter to reduce random noise.

### 4.2. Self capacitance mode

CHSC5816 has high performance self -cap detect technique, the self cap detect with 4 sub-mode can adaptive numerous application, with strong noise immunity and high sensitivity. Also can support large self -capacitance range

### 4.3. Noise detection

The CTP can scan large frequency range and get noise power density of touch screen, and then system can choose a working frequency with less noise.

### 4.4 Short detection

At short detection mode, the CTP will sense the resistance of RX Pin, and it is very helpful to factory production.

## 五、Communication interface

### 5.1. I2C communication description

I2C module of the CHSC5816 acts as slave. Its related registers are as follows:

Be default, I2C Master can read any internal register and RAM space of the CHSC5816 via I2C.

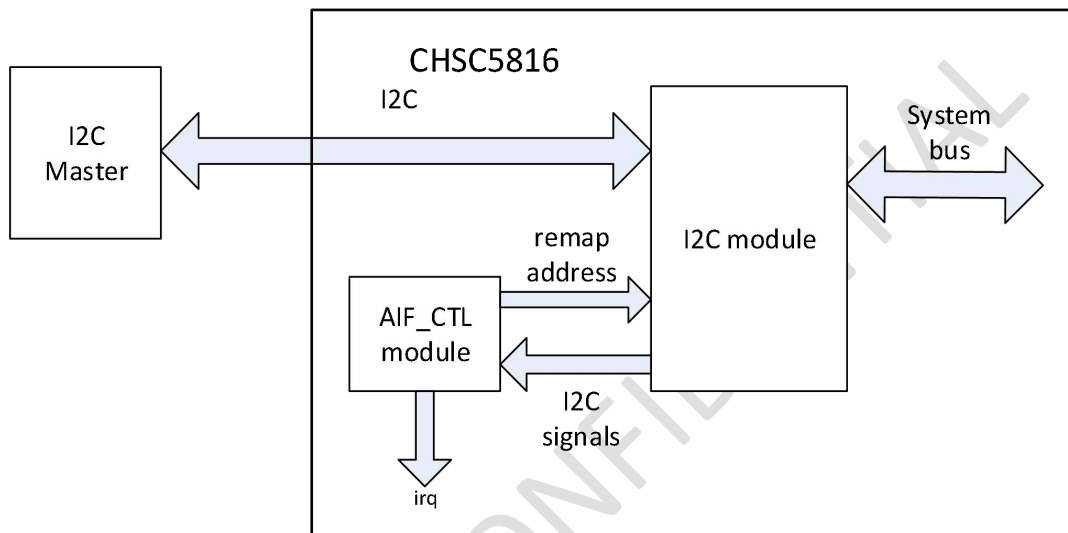


Figure 5-1 Connection schematic between I2C and AIF\_CTL module

The AIF\_CTL module embedded in the CHSC5816 serves to implement I2C address mapping, and provide command register to generate interrupt signal for I2C communication.

### 5.2 I2C timing

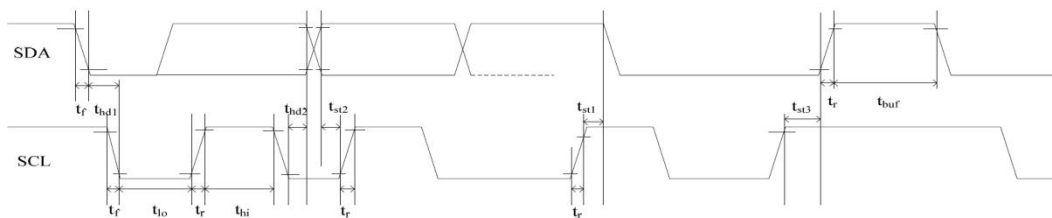


Figure 5-2 I2C timing sequence



Table 5-1 I2C timing parameter

| parameter                          | symbol    | MIN | MAX | unit |
|------------------------------------|-----------|-----|-----|------|
| SCL low period                     | $t_{lo}$  | 1.3 |     | us   |
| SCL high period                    | $t_{hi}$  | 0.6 |     | us   |
| SCL setup time for START condition | $t_{st1}$ | 0.6 |     | us   |
| SCL setup time for STOP condition  | $t_{st3}$ | 0.6 |     | us   |
| SCL hold time for START condition  | $t_{hd1}$ | 0.6 |     | us   |
| SDA setup time                     | $t_{st2}$ | 0.1 |     | us   |
| SDA hold time                      | $t_{hd2}$ | 0   |     | us   |

### 5.3 AC characteristics

Table5-2 AC Characteristics

| Parameter              | Sym.     | Min            | Typ. | Max           | Unit | Condition |
|------------------------|----------|----------------|------|---------------|------|-----------|
| Digital inputs/outputs |          |                |      |               |      |           |
| IO voltage(*)          | VDDIO    | 1.6            | 1.8  | 2             | V    |           |
| IO voltage(**)         | VDDIO    | 3.0            | 3.3  | 3.6           | V    |           |
| Input high voltage     | $V_{IH}$ | $0.7V_{DDIO}$  |      | $V_{DDIO}$    | V    |           |
| Input low voltage      | $V_{IL}$ | VSS            |      | $0.3V_{DDIO}$ | V    |           |
| Output high voltage    | $V_{OH}$ | $V_{DDIO}-0.3$ |      | VDD           | V    |           |
| Output low voltage     | $V_{OL}$ | VSS            |      | 0.3           | V    |           |

(\*)VDDIO = 1.8V @ VDD28 = 2.8V

(\*)VDDIO =1.8V/3.3V @ VDD28=3.3V

## 六、Power on reset sequence

Reset should be pulled down to be low before powering on and powering down. I2C shouldn't be used by other devices during Reset time after VDD powering on ( $T_{rtp}$ ). INT signal will be sent to the host after initializing all parameters and then start to report points to the host. If Power is down, the voltage of supply must be below 0.3V and  $T_{pdt}$  is more than 1ms.

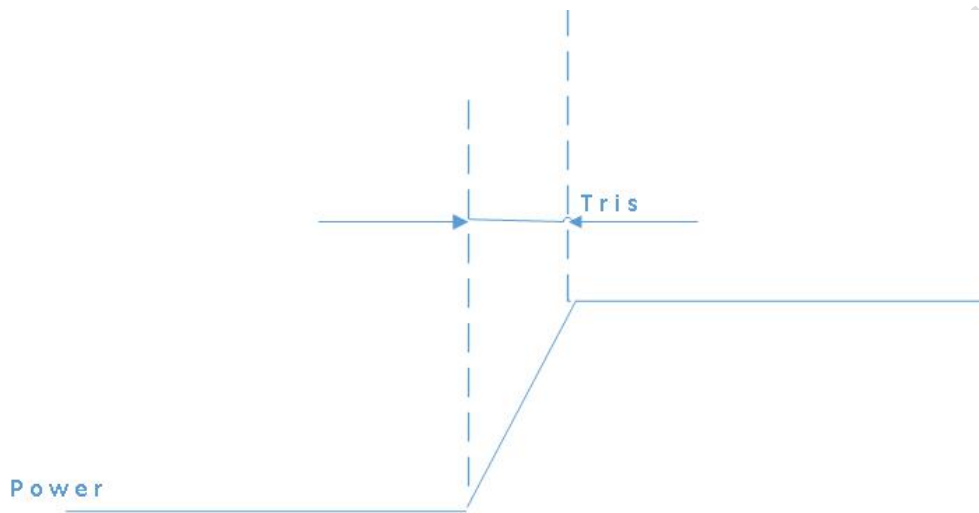


Figure 6-1 power on time

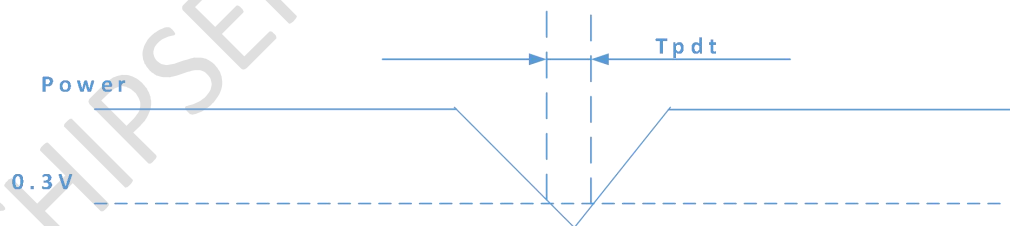


Figure 6-2 Power Cycle requirement

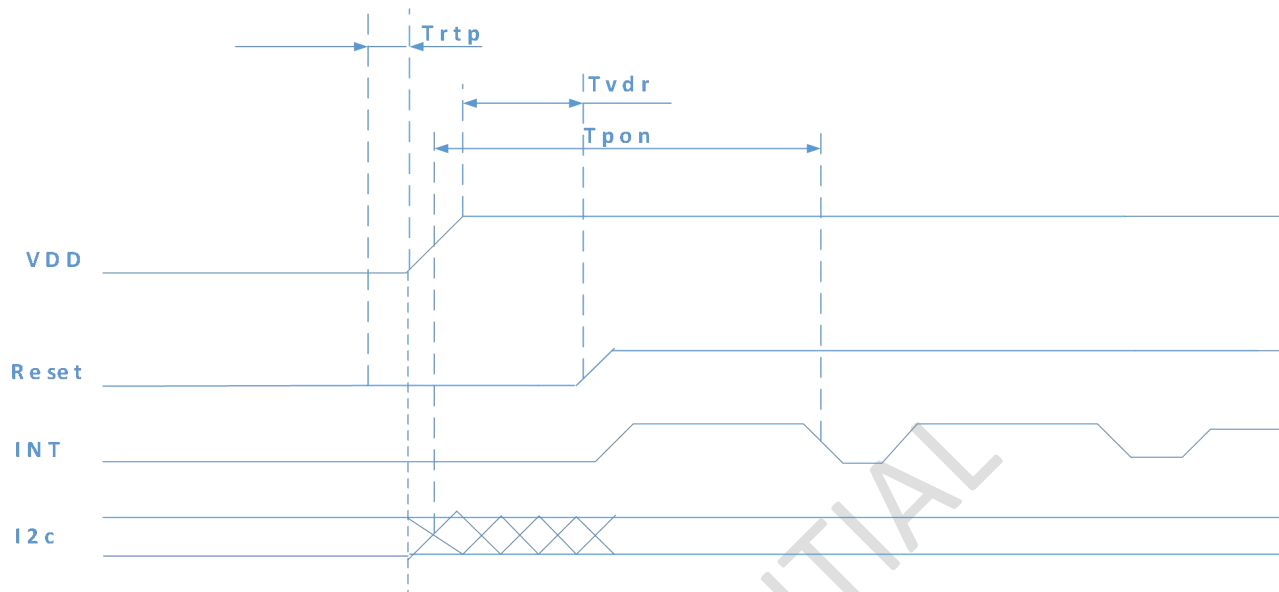


Figure 6-3 Power on Sequence

Reset time must be enough to guarantee reliable reset, the time of starting to report point after resetting approach to the time of starting to report point after powering on.

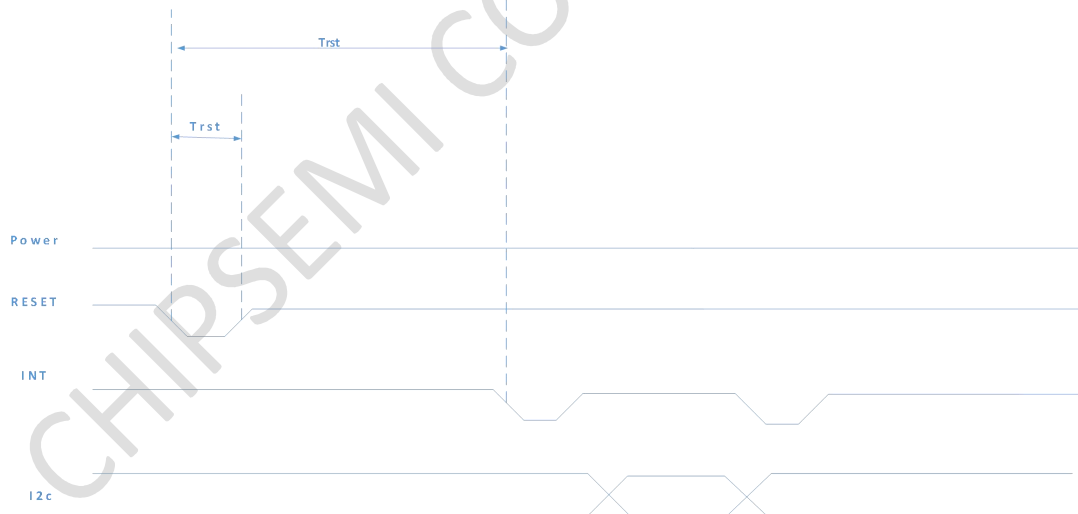


Figure 6-4 Reset Sequence

Table 6-1 Power on/Reset Sequence Parameters

| Parameter | Description  | Min | Max | Units   |
|-----------|--|-----|-----|---------|
| Tris      | Rise time from 0.1VDD to 0.9VDD                    | --  | 5   | ms      |
| Tpdt      | Time of the voltage of supply being below 0.3V     | 2   | --  | ms      |
| Trtp      | Time of resetting to be low before powering on     | 100 | --  | $\mu$ s |
| Tpon      | Time of starting to report point after powering on | --  | 200 | ms      |
| Tvdr      | Reset time after VDD powering on                   | 1   | --  | ms      |
| Trsi      | Time of starting to report point after resetting   | --  | 200 | ms      |
| Trst      | Reset time   | 500 | --  | us      |

## 七、System application guide

The CHSC5816 supply voltage can use 2.8V or 3.3V, support 1.8V or 3.3V IO voltage to system. This circuit has a 1.8V LDO internally, user can use it to pull up I2C resister or not.

If VDD18 pin connect to VDD28, the 1.8V LDO will be disabled automatically.

### 7.1. Application

There are two applications for connections.

**Application 1:** VCCA = 2.8V/3.3V, I2C communication voltage = VBUS

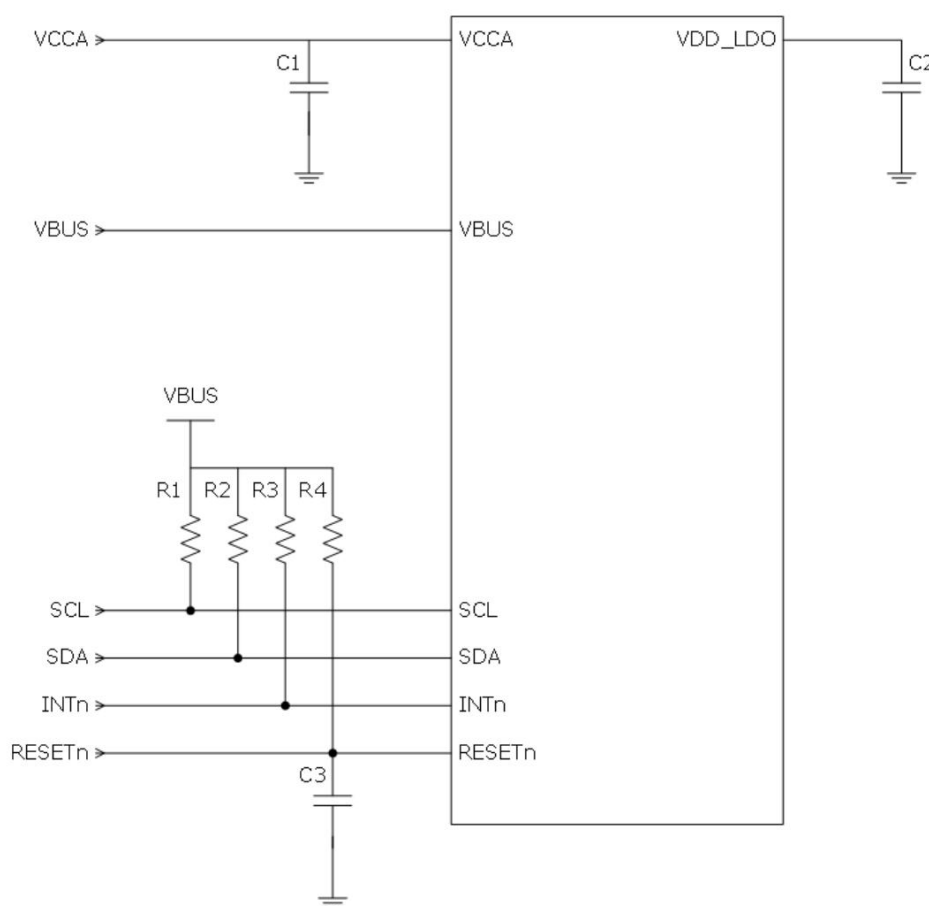


Figure 7-1 I2C host interface

**Note :** the C3 at RSTN pin can be removed if no serious noise couple to RSTN pin.

## Application 2: VCCA = 2.8V/3.3V

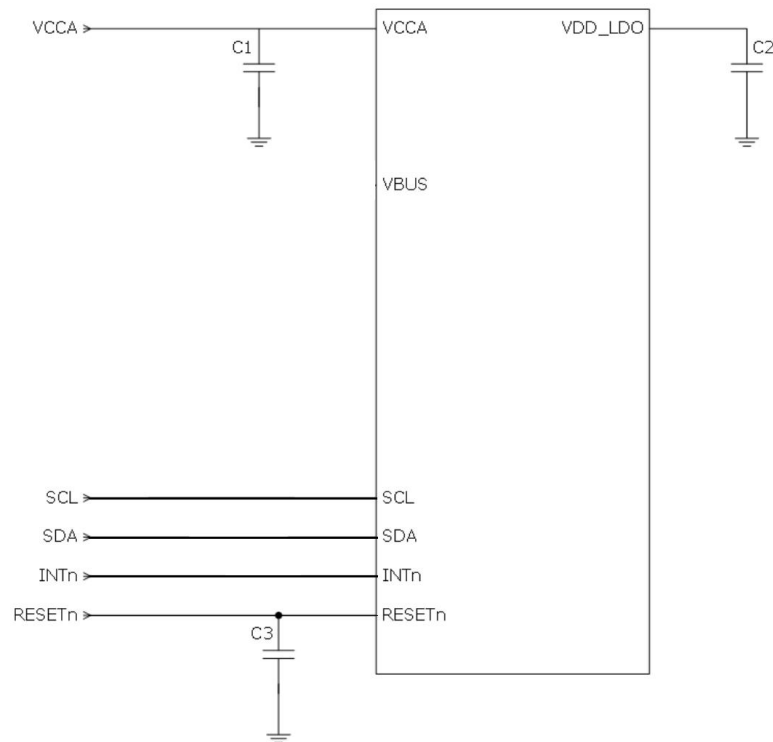


Figure 7-2 I2C host interface

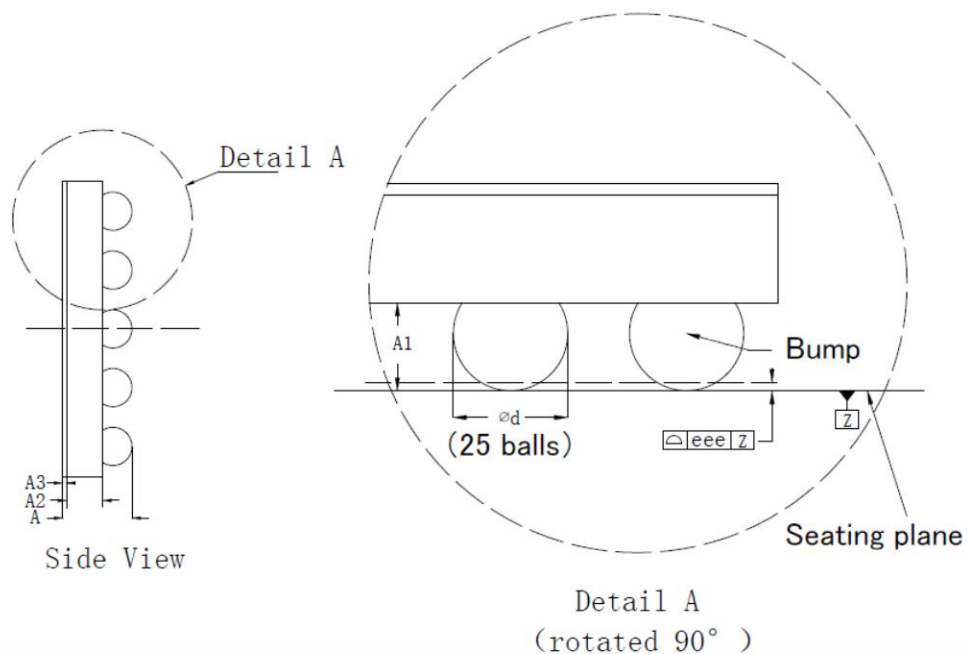
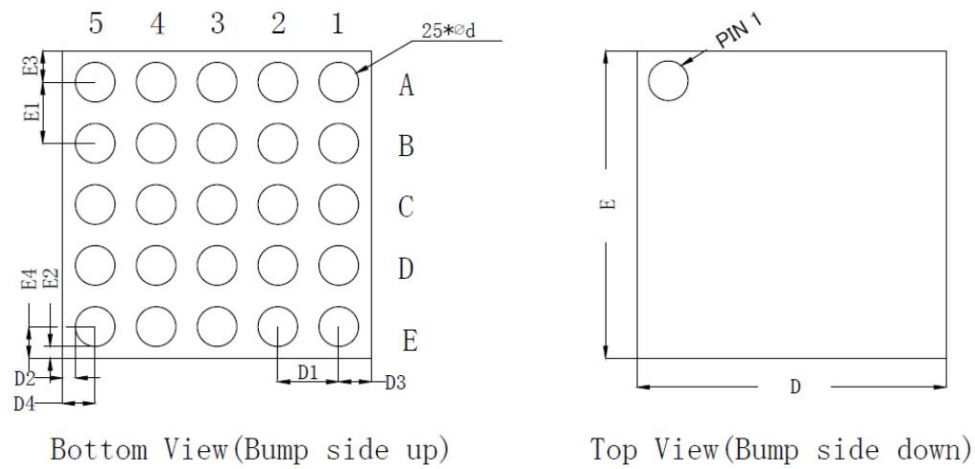
Note : the C3 at RSTN pin can be removed if no serious noise couple to RSTN pin.

## 7.2. Package information

Figure 7-3 Package top view and side view

Table1: Package Dimension

| Parameter                | Symbol | Nominal     | Min    | Max    | NOTE     |
|--------------------------|--------|-------------|--------|--------|----------|
|                          |        | Millimeters |        |        |          |
| Package Body Dimension X | D      | 2.0308      | 2.0108 | 2.0508 | ± 0.020  |
| Package Body Dimension Y | E      | 2.0128      | 1.9928 | 2.0328 | ± 0.020  |
| Package Height           | A      | 0.470       | 0.440  | 0.500  | ± 0.030  |
| Solder Bump Height       | A1     | 0.200       | 0.180  | 0.220  | ± 0.020  |
| Si thickness             | A2     | 0.245       | 0.2325 | 0.2575 | ± 0.0125 |
| BC thickness             | A3     | 0.025       | 0.020  | 0.030  | ± 0.005  |
| Solder Bump Diameter     | d      | 0.260       | 0.240  | 0.280  | ± 0.020  |
| Coplanarity              | eee    | 0.020       |        |        | /        |
| Ball Pitch X axis (min.) | D1     | 0.400       |        |        | /        |
| Ball Pitch Y axis (min.) | E1     | 0.400       |        |        | /        |
| Ball edge to die edge    | D2     | 0.08541     |        |        | /        |
| Ball edge to die edge    | E2     | 0.07641     |        |        | /        |
| Ball center to die edge  | D3     | 0.21541     |        |        | /        |
| Ball center to die edge  | E3     | 0.20641     |        |        | /        |
| Ball center to die edge  | D4     | 0.21541     |        |        | /        |
| Ball center to die edge  | E4     | 0.20641     |        |        | /        |



#### NOTES

- 1.REFER TO JEDEC MO-220;
- 2.COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD;
- 3.BAN TO USE THE LEVEL 1 ENVIRONMENT-RELATED SUBSTANCES;
- 4.FINISH: Cu/EP • Sn8~20s

Table 7-1 Ordering information of the CHSC5816

| Product Series | Package Type                             | Temperature Range | Product Part No. | Packing Method | Ordering Number | Minimum Order Quantity |
|----------------|--|-------------------|------------------|----------------|-----------------|------------------------|
| CHSC5816       | 25-pin<br>WLCSP:<br>2.01x1.99x0.44<br>mm | -40℃<br><br>~+85℃ | CHSC5816         | TR             | CHSC5816R       | 3000                   |

\*Note: Packing method “TR” means tape and reel.